# **BUK9M8R5-40H**

N-channel 40 V, 8.5 mΩ logic level MOSFET in LFPAK33

29 January 2019

Product data sheet

# 1. General description

Automotive qualified logic level N-channel MOSFET in an LFPAK33 package using Trench 9 TrenchMOS technology. This product has been designed and qualified to AEC-Q101 for use in high performance automotive applications.

# 2. Features and benefits

- Fully automotive qualified to AEC-Q101 at 175 °C
- Trench 9 superjunction technology:
  - · Low power losses, high power density
- · LFPAK copper clip package technology:
  - · High robustness and reliability
  - · Gull wing leads for high manufacturability and AOI
- Repetitive avalanche rated

# 3. Applications

- 12 V automotive systems
- · Powertrain, chassis, body and infotainment applications
- · Medium/Low power motor drive
- · DC-DC systems
- · LED lighting

## 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C		-	-	40	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[1]	-	-	40	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	-	59	W
Static characte	ristics						
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ Fig. 11		5	7.2	8.5	mΩ
Dynamic chara	cteristics		•	•			
$Q_{GD}$	gate-drain charge	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 4.5 V; Fig. 13; Fig. 14		-	2.1	4.2	nC
Source-drain d	iode						
Q <sub>r</sub>	recovered charge	$I_S = 15 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V}; V_{DS} = 20 \text{ V}$		-	15	-	nC



Symbol	Parameter	Conditions	Min	Тур	Max	Unit
S		$I_S$ = 15 A; $dI_S/dt$ = -100 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; $T_j$ = 25 °C; Fig. 17	-	0.61	-	

<sup>[1] 40</sup>A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

# 5. Pinning information

### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		D -
2	S	source	]	
3	S	source		G—(F)
4	G	gate		mbb076 S
mb	D	Mounting base; connected to drain	1 2 3 4 LFPAK33 (SOT1210	0)

# 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package	ackage						
	Name	Description	Version					
BUK9M8R5-40H	LFPAK33	Plastic, single ended surface mounted package (LFPAK33); 8 leads; 0.65 mm pitch	SOT1210					

# 7. Marking

# Table 4. Marking codes

Type number	Marking code
BUK9M8R5-40H	98H040

# 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C		-	40	V
$V_{GS}$	gate-source voltage	DC; T <sub>j</sub> ≤ 175 °C		-10	16	V
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	59	W
I <sub>D</sub>	drain current	V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[1]	-	40	А
		V <sub>GS</sub> = 10 V; T <sub>mb</sub> = 100 °C; <u>Fig. 2</u>		-	40	А
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 °C$ ; Fig. 3		-	239	А
T <sub>stg</sub>	storage temperature			-55	175	°C
Tj	junction temperature			-55	175	°C
Source-drain	n diode		•		•	

Symbol	Parameter	Conditions		Min	Max	Unit
Is	source current	T <sub>mb</sub> = 25 °C		-	40	Α
I <sub>SM</sub>	peak source current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 °C$		-	239	Α
Avalanche rugg	edness					
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	$I_D$ = 40 A; $V_{sup} \le 40$ V; $R_{GS}$ = 50 Ω; $V_{GS}$ = 10 V; $T_{j(init)}$ = 25 °C; unclamped; Fig. 4	[2] [3]	-	24	mJ

- 40A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.
- [2] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C.
- [3] Refer to application note AN10273 for further information.

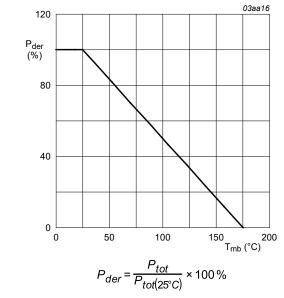
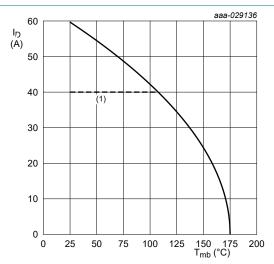


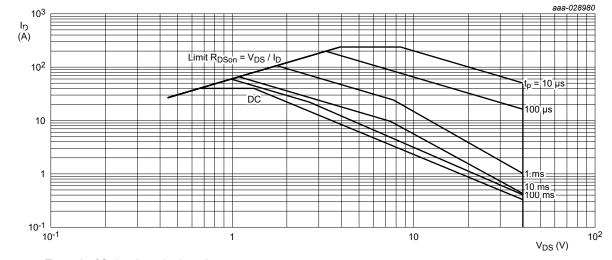
Fig. 1. Normalized total power dissipation as a function of mounting base temperature



 $V_{GS} \ge 10 \text{ V}$ 

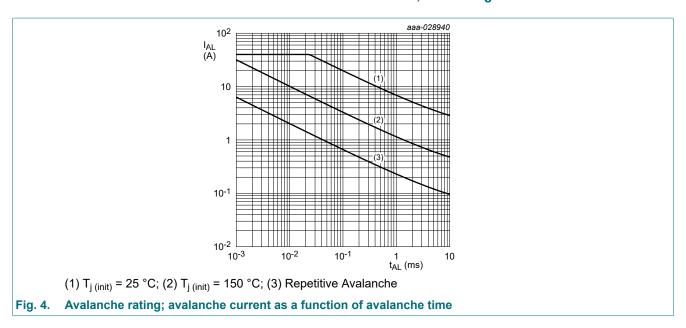
(1) 40A continuous current has been successfully demonstrated during application tests. Practically the current will be limited by PCB, thermal design and operating temperature.

Fig. 2. Continuous drain current as a function of mounting base temperature



T<sub>mb</sub> = 25 °C; I<sub>DM</sub> is a single pulse

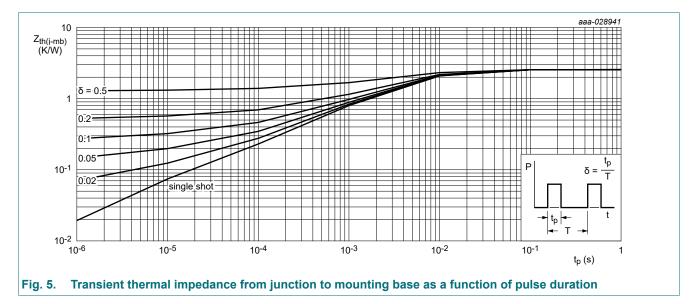
Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage



# 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	<u>Fig. 5</u>	-	2.33	2.56	K/W



# 10. Characteristics

Table 7. Characteristics

Table 11 enalectioned							
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static chara	cteristics		•				
V <sub>(BR)DSS</sub>	drain-source	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C		40	43	-	V
	breakdown voltage	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -40 ^{\circ} C$		-	40.5	-	V

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
		I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>i</sub> = -55 °C	36	40	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	I <sub>D</sub> = 1 mA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>j</sub> = 25 °C; <u>Fig. 9</u> ; <u>Fig. 10</u>	1.45	1.77	2.15	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>i</sub> = -55 °C; <u>Fig. 10</u>	-	-	2.6	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>j</sub> = 175 °C; Fig. 10	0.7	-	-	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	0.02	1	μΑ
		V <sub>DS</sub> = 16 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 125 °C	-	0.42	10	μΑ
		V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C	-	30	500	μΑ
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 16 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	2	100	nA
		V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	2	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	$V_{GS}$ = 10 V; $I_D$ = 15 A; $T_j$ = 25 °C; Fig. 11	5	7.2	8.5	mΩ
		$V_{GS}$ = 10 V; $I_D$ = 15 A; $T_j$ = 105 °C; Fig. 12	6.8	10.2	12.8	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 125 °C; Fig. 12	7.5	11.1	13.7	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 175 °C; Fig. 12	9.1	13.5	16.5	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 25 °C; Fig. 11	6.3	9	11	mΩ
		V <sub>GS</sub> = 4.5 V; I <sub>D</sub> = 15 A; T <sub>j</sub> = 105 °C; Fig. 12	8.6	12.7	16.5	mΩ
		$V_{GS}$ = 4.5 V; $I_{D}$ = 15 A; $T_{j}$ = 125 °C; Fig. 12	9.5	13.8	17.7	mΩ
		$V_{GS}$ = 4.5 V; $I_{D}$ = 15 A; $T_{j}$ = 175 °C; Fig. 12	11.5	16.7	21.4	mΩ
R <sub>G</sub>	gate resistance	f = 1 MHz; T <sub>j</sub> = 25 °C	0.3	0.8	2	Ω
Dynamic ch	naracteristics					
Q <sub>G(tot)</sub>	total gate charge	I <sub>D</sub> = 15 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 10 V; Fig. 13; Fig. 14	-	20	28	nC
		I <sub>D</sub> = 15 A; V <sub>DS</sub> = 20 V; V <sub>GS</sub> = 4.5 V;	-	9	13	nC
Q <sub>GS</sub>	gate-source charge	Fig. 13; Fig. 14	-	3.6	5.4	nC
Q <sub>GD</sub>	gate-drain charge		-	2.1	4.2	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0 V; f = 1 MHz;	-	1286	1800	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C; <u>Fig. 15</u>	-	345	483	pF
C <sub>rss</sub>	reverse transfer capacitance		-	49	108	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = 20 \text{ V}; R_L = 1.2 \Omega; V_{GS} = 4.5 \text{ V};$	-	9.5	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 5 \Omega$	-	9.4	-	ns
$t_{d(off)}$	turn-off delay time	1	-	11	-	ns
t <sub>f</sub>	fall time	1	-	5.6	-	ns
Source-dra	in diode		1			
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = 15 A; V <sub>GS</sub> = 0 V; T <sub>i</sub> = 25 °C; <u>Fig. 16</u>	-	0.85	1.2	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = 15 A; dI <sub>S</sub> /dt = -100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 20 V; Fig. 17	-	22	-	ns
Q <sub>r</sub>	recovered charge	I <sub>S</sub> = 15 A; dI <sub>S</sub> /dt = -100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 20 V	-	15	-	nC

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
S	softness factor	$I_S = 15 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$ $V_{DS} = 20 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 17$	-	0.61	-	
		$I_S$ = 15 A; $dI_S/dt$ = -500 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; $T_j$ = 25 °C; Fig. 17	-	0.41	-	

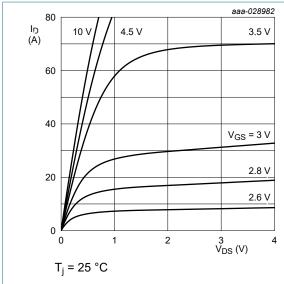


Fig. 6. Output characteristics; drain current as a function of drain-source voltage; typical values

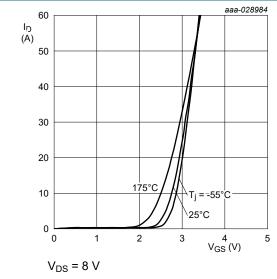


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

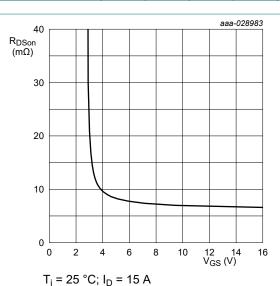


Fig. 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

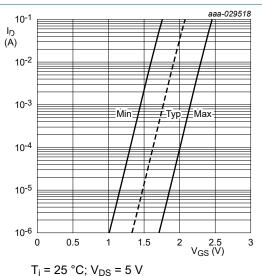


Fig. 9. Sub-threshold drain current as a function of gate-source voltage

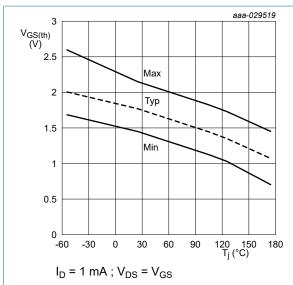


Fig. 10. Gate-source threshold voltage as a function of junction temperature

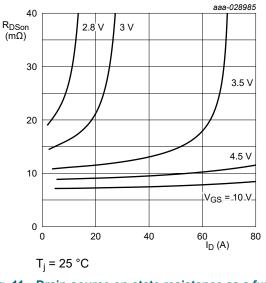


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

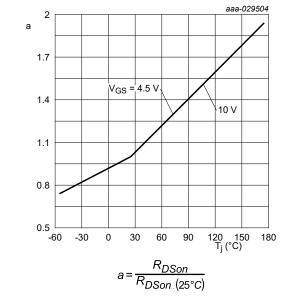


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

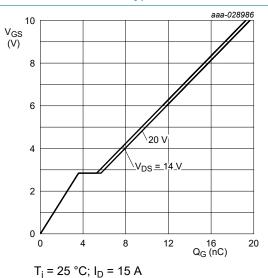


Fig. 13. Gate-source voltage as a function of gate charge; typical values

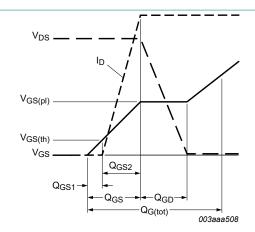
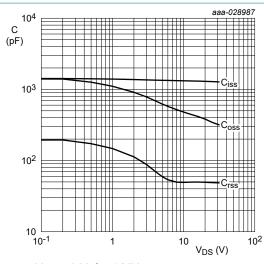


Fig. 14. Gate charge waveform definitions



 $V_{GS} = 0 V$ ; f = 1 MHz

Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

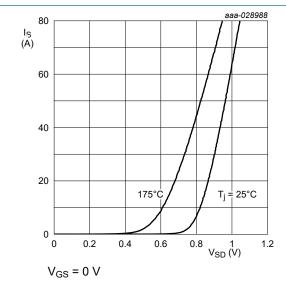


Fig. 16. Source-drain (diode forward) current as a function of source-drain (diode forward) voltage; typical values

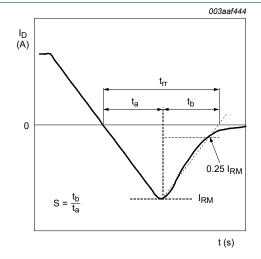


Fig. 17. Reverse recovery timing definition

# 11. Package outline

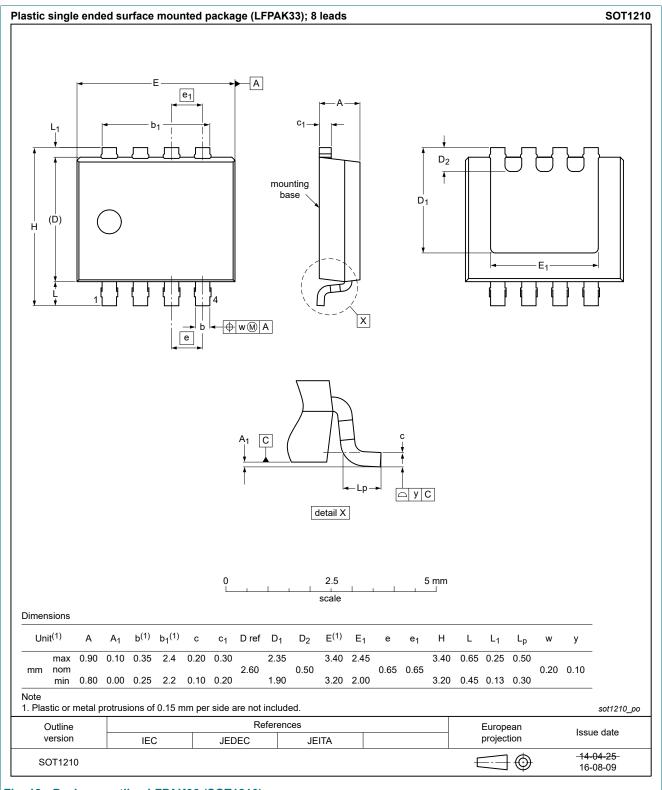


Fig. 18. Package outline LFPAK33 (SOT1210)

# 12. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 29 January 2019

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